

Title (en)  
ELECTRICAL CONNECTING DEVICE WITH HIGH CONTACT DENSITY

Publication  
**EP 0053968 B1 19850130 (FR)**

Application  
**EP 81401870 A 19811125**

Priority  
FR 8025861 A 19801205

Abstract (en)  
[origin: US4445735A] The invention provides an electrical connection device for connecting high density contacts of large scale integrated circuits (LSI) and serves to establish electrical connection between the contact areas (15) of the circuit network (14) on a substrate (11) for supporting integrated circuit devices (12) and the contact pads (18) of a conductor network (17) on a printed circuit card (13). The electric connection device comprises a plurality of conductive elements disposed within a housing (26) extending in a given direction. The conductive elements are electrically insulated one from the other and have contacts which are exposed through slots in the housing to connect to the areas (15) and pads (18). The conductive elements (29) are stacked in the given direction and are formed each with a conductor sheet (30) provided with two contact surfaces (31a, 32a) elastically movable in a plane normal to the given direction independently of the surfaces of contact of neighboring sheets. The conductor sheet are supported on elastically deformable rolls extending the length of the support means which enable the contact surfaces to be displaced and compensate for deformities in the substrate and manufacturing tolerances.

IPC 1-7  
**H01R 23/72**

IPC 8 full level  
**H01R 11/01** (2006.01); **H01L 21/60** (2006.01); **H01R 12/55** (2011.01); **H05K 1/18** (2006.01); **H05K 3/32** (2006.01)

CPC (source: EP US)  
**H01R 12/714** (2013.01 - EP US)

Cited by  
EP0384438A1; US4952156A; EP0359223A1; FR2636491A1

Designated contracting state (EPC)  
CH DE FR GB IT LI NL

DOCDB simple family (publication)  
**EP 0053968 A1 19820616; EP 0053968 B1 19850130**; DE 3168702 D1 19850314; FR 2495846 A1 19820611; FR 2495846 B1 19840106; JP H0250589 B2 19901102; JP S57121176 A 19820728; US 4445735 A 19840501

DOCDB simple family (application)  
**EP 81401870 A 19811125**; DE 3168702 T 19811125; FR 8025861 A 19801205; JP 19463881 A 19811204; US 32653081 A 19811202